SiHF7N60E

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GDS

TO-220 FULLPAK

PRODUCT SUMMARY

V_{DS} (V) at T_J max.

Q_q max. (nC)

Configuration

Q_{gs} (nC)

Q_{gd} (nC)

R_{DS(on)} max. (Ω) at 25 °C

Vishay Siliconix

E Series Power MOSFET

S

N-Channel MOSFET

0.6

650

40

5

9

Single

V_{GS} = 10 V



- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-220 FULLPAK
Lead (Pb)-free	SiHF7N60E-E3
Lead (Pb)-free and Halogen-free	SiHF7N60E-GE3

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		M	600	
Drain-Source voltage	$T_{C} = -25 \text{ °C}, I_{D} = 250 \mu\text{A}$	V _{DS}	575	V
Gate-Source Voltage		V _{GS}	± 30	
Continuous Drain Current $(T_{1} - 150^{\circ}C)^{\circ}$	$V_{GS} \text{ at } 10 \text{ V} \qquad \frac{T_{C} = 25 \text{ °C}}{T_{C} = 100 \text{ °C}}$	1-	7	
Continuous Drain Current (T _J = 150 $^{\circ}$ C) e	$T_{\rm C} = 100 ^{\circ}{\rm C}$	I _D	5	А
Pulsed Drain Current ^a		I _{DM}	18	
Linear Derating Factor			0.25	W/°C
Single Pulse Avalanche Energy ^b		E _{AS}	43	mJ
Maximum Power Dissipation		PD	31	W
Operating Junction and Storage Temperature Range	e	T _J , T _{stg}	-55 to +150	°C
Drain-Source Voltage Slope	T _J = 125 °C	d\//d+	70	
Reverse Diode dV/dt ^d		dV/dt	3	V/ns
Soldering Recommendations (Peak temperature) ^c	For 10 s		300	°C
Mounting Torque	M3 screw		0.6	Nm

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.

b. $V_{DD} = 50$ V, starting $T_J = 25$ °C, L = 13.8 mH, $R_g = 25 \Omega$, $I_{AS} = 2.5$ A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C.

e. Limited by maximum junction temperature.

S16-1602-Rev. E, 15-Aug-16

1

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THERMAL RESISTANCE RATI								
PARAMETER	SYMBOL	TYP.		MAX.			UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-		65			°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-		4.0			0,11	
SPECIFICATIONS ($T_J = 25 \text{ °C}$, u								
PARAMETER	SYMBOL	TES	T CONDIT	IONS	MIN.	TYP.	MAX.	UNIT
Static		T				I	1	1
Drain-Source Breakdown Voltage	V _{DS}		= 0 V, I _D =		609	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 1 mA	-	0.68	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2	-	4	V
Gate-Source Leakage	lass		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Cate Cource Leakage	I _{GSS}		$V_{GS} = \pm 30$	V	-	-	± 1	μA
Zara Cata Valtaga Drain Current		V _{DS} =	= 600 V, V _G	_{is} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 480 V	/, V _{GS} = 0 V	/, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 V$	l	_D = 3.5 A	-	0.5	0.6	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 50 V, I _D =	= 3.5 A	-	1.9	-	S
Dynamic								
Input Capacitance	C _{iss}	$V_{r,r} = 0 V_{r}$		-	680	-		
Output Capacitance	C _{oss}		V _{GS} = 0 V, V _{DS} = 100 V,		-	39	-	1
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz		-	5	-	pF	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}			-	34	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$V_{\rm DS} = 0.0$	/ to 480 V,	V _{GS} = 0 V	_	100	-	
Total Gate Charge	Qg				-	20	40	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	I _D = 3.5	A, V _{DS} = 480 V	-	5	-	nC
Gate-Drain Charge	Q _{gd}				-	9	-	
Turn-On Delay Time	t _{d(on)}				-	13	26	
Rise Time	t _r		490 1/ 1	- 2 5 4	-	13	26	1
Turn-Off Delay Time	t _{d(off)}	- v _{DD} = V _{CS} =	= 480 V, I _D = 10 V, R _q :	= 3.3 A, = 9.1 Ω	-	24	48	ns
Fall Time	t _f		, y		-	14	28	
Gate Input Resistance	R _g	f = 1	MHz, ope	n drain	-	1.1	-	Ω
Drain-Source Body Diode Characteristic							1	1
Continuous Source-Drain Diode Current	I _S	MOSFET sym	MOSFET symbol		-	-	7	
Pulsed Diode Forward Current	I _{SM}	integral revers p - n junction			-	-	18	A
Diode Forward Voltage	V _{SD}	T _{.1} = 25 °C	C, I _S = 3.5 /	A, V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}	<u> </u>	, , , , , , , , , , , , , , , , , , , ,	, 40	-	230	-	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25$	5 °C, I _F = I _S	s = 3.5 A,	-	1.9	-	μC
Reverse Recovery Current	I _{RRM}	dl/dt =	100 A/µs,	V _R = 20 V	-	14	-	μ0 A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

Document Number: 91509



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

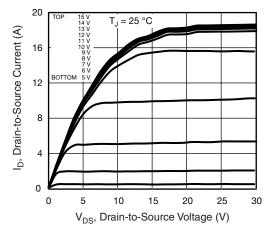


Fig. 1 - Typical Output Characteristics

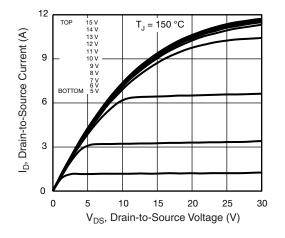


Fig. 2 - Typical Output Characteristics

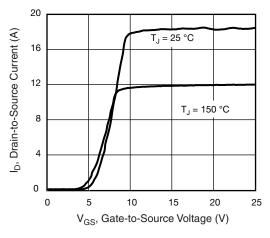


Fig. 3 - Typical Transfer Characteristics

S16-1602-Rev. E, 15-Aug-16

Fig. 4 - Normalized On-Resistance vs. Temperature

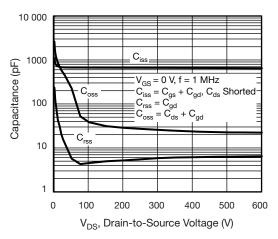


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

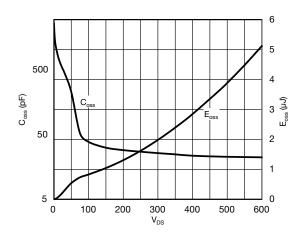


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}

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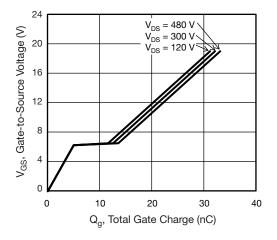


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

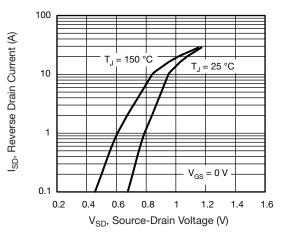
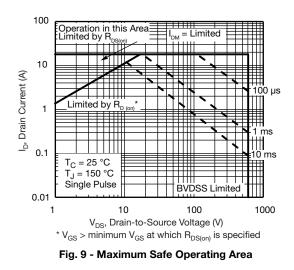


Fig. 8 - Typical Source-Drain Diode Forward Voltage



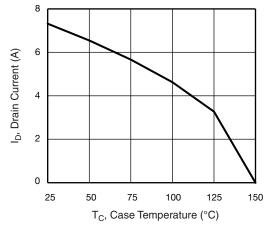


Fig. 10 - Maximum Drain Current vs. Case Temperature

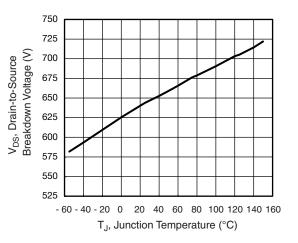
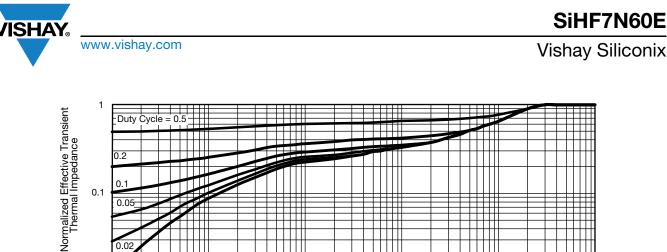


Fig. 11 - Temperature vs. Drain-to-Source Voltage

4

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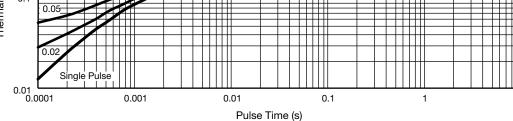


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

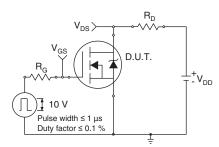


Fig. 13 - Switching Time Test Circuit

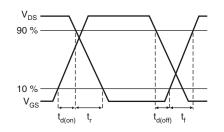


Fig. 14 - Switching Time Waveforms

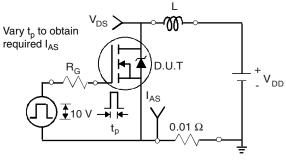


Fig. 15 - Unclamped Inductive Test Circuit

10

Fig. 16 - Unclamped Inductive Waveforms

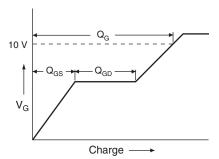


Fig. 17 - Basic Gate Charge Waveform

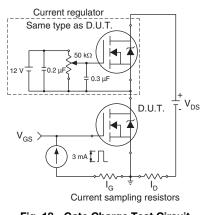


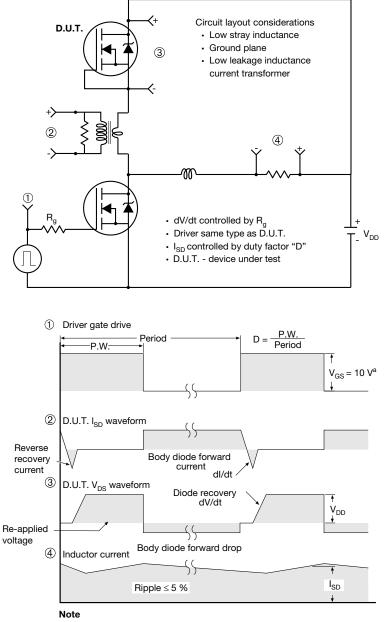
Fig. 18 - Gate Charge Test Circuit

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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5 V$ for logic level devices

Fig. 19 - For N-Channel

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TO-220 FULLPAK (High Voltage)

OPTION 1: FACILITY CODE = 9



		MILLIMETERS	
DIM.	MIN.	NOM.	MAX.
A	4.60	4.70	4.80
b	0.70	0.80	0.91
b1	1.20	1.30	1.47
b2	1.10	1.20	1.30
С	0.45	0.50	0.63
D	15.80	15.87	15.97
е		2.54 BSC	
E	10.00	10.10	10.30
F	2.44	2.54	2.64
G	6.50	6.70	6.90
L	12.90	13.10	13.30
L1	3.13	3.23	3.33
Q	2.65	2.75	2.85
Q1	3.20	3.30	3.40
ØR	3.08	3.18	3.28

Notes

- 1. To be used only for process drawing
- 2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads
- 3. All critical dimensions should C meet $C_{pk} > 1.33$
- 4. All dimensions include burrs and plating thickness
- 5. No chipping or package damage
 6. Facility code will be the 1st character located at the 2nd row of the unit marking



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OPTION 2: FACILITY CODE = Y



MILLIMETERS		IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
С	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
е	2.54	BSC	0.100 BSC	
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
ØP	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

DWG: 5972

Notes

1. To be used only for process drawing

2. These dimensions apply to all TO-220 FULLPAK leadframe versions 3 leads

3. All critical dimensions should C meet $C_{pk} > 1.33$

4. All dimensions include burrs and plating thickness

5. No chipping or package damage
6. Facility code will be the 1st character located at the 2nd row of the unit marking

2

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